

Product Change Notification - KSRA-14RYZT111

Date: 22 Sep 2017
Product Category: 32-bit PIC Microcontrollers
Notification subject: CCB 2972 Final Notice: Qualification of MTAI as an additional assembly site for selected Atmel Products available in 64L TQFP (10x10x1.0mm) package using CuPdAu bond wire
Notification text: **PCN Status:**
 Final notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MTAI as an additional assembly site for selected Atmel products available in 64L TQFP (10x10x1.0mm) package using palladium coated copper wire with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ASCL and ASE Assembly site

Post Change:

Assembled at ASCL, ASE and MTAI Assembly site

Pre and Post Change Summary:

	Pre Change		Post Change		
	ASCL	ASE	ASCL	ASE	MTAI
Assembly Site	ASCL	ASE	ASCL	ASE	MTAI
Wire material	Au/CuPdAu	CuPdAu	Au/CuPdAu	CuPdAu	CuPdAu
Die attach material	EN-4900GC	CRM-1076WA	EN-4900GC	CRM-1076WA	3280
Molding compound material	G700HA	G631H	G700HA	G631H	G700HA
Lead frame material	C194	C7025	C194	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MTAI assembly site

Change Implementation Status:

In Progress

Estimated First Ship Date :

October 22, 2017 (1743)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	June 2017					-->	September 2017					October 2017				
	22	23	24	25	26		35	36	37	38	39	40	41	42	43	44
Initial PCN Issue Date				X												
Qual Report Availability									X							
Final PCN Issue Date									X							
Estimated Implementation Date														X		

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

June 21, 2017: Issued initial notification.
September 22, 2017: Issued final notification. Revised the subject and description to include CuPdAu. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on October 22, 2017

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_KSRA-14RYZT111_Affected CPN.pdf](#)
[PCN_KSRA-14RYZT111_Qual Report.pdf](#)
[PCN_KSRA-14RYZT111_Affected CPN.xlsx](#)

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-14RYZT111
CATALOG_PART_NBR
ATSAMD21J15B-AF
ATSAMD21J15B-AFT
ATSAMD21J15B-AU
ATSAMD21J15B-AUT
ATSAMD21J16B-AF
ATSAMD21J16B-AFT
ATSAMD21J16B-AU
ATSAMD21J16B-AUT
ATSAMDA1J14B-ABT
ATSAMDA1J15B-ABT
ATSAMDA1J16B-ABT